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Product Name:

Surface Mount Backflow Soldering Machine

Product Code:
ENGLABINGCAG5200001



Description:

Surface Mount Backflow Soldering Machine

Technical Specification:

In welding process, PCB is in static state/ The surface components should be in correct position, and avoid not be soldering.

Soldering zone use far infrared ray heat, and high temperature motor force to be heated.

Equip with nitrogen protection connector, and use nitrogen to make protection.

Soldering zone use fuzzy control technology, you can only set 3 units of technical parameter, then you can control the whole temperature curve, and you can follow temperature change, blue backlight LCD display. It use 320×240mm dot matrix high resolution LCD display, the dimension of LCD is 113mm Dot matrix high resolution LCD 80mm.

The solding machine can be connected to PC, and use backflow curve to record save software.

The welding machine has 4 ways temperature sensor interface, sensor head is PT100, it can correct welding temperature curve through backflow analysis

Peak power: 3.5KW



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